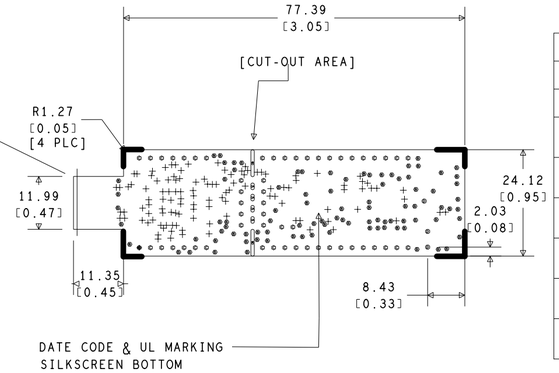
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	ALPHA RELEASE	23/09/16	NMIT
2	BETA RELEASE	02/11/16	NMIT
3	J2.14 CHANGED TO VDDD	08/11/16	NMIT
4	SILK CHANAGES	01/17/17	NMIT
05	SILK CHANAGES	02/02/17	NMIT

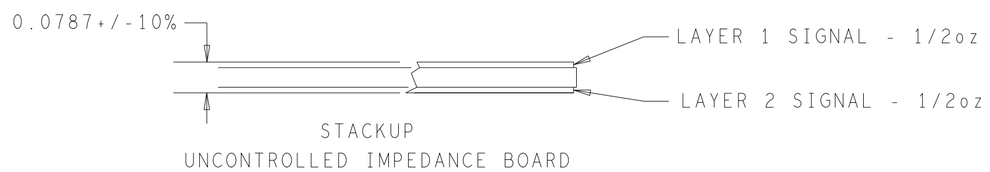
Note: "Edge Bevelling and Chamfering at 45 degree for the USB Finger edge connector"



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	10.0	+3.0/-3.0	PLATED	114
•	13.0	+3.0/-3.0	PLATED	92
◦	40.0	+3.0/-3.0	PLATED	54
◦	43.0	+3.0/-3.0	PLATED	3
▫	60.0x30.0	+2.0/-2.0	NON-PLATED	4
▯	240.0x30.0	+2.0/-2.0	NON-PLATED	2

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol.
      UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
      COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE
      BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE
      MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED
      ARE 1:1. SOLDERMASK COLOR **RED*
7. FINISH:
   A. SHALL BE ELECTROLESS NIKEL / IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY.
   FLAMABILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD
   IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN
      THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.



STACKUP
UNCONTROLLED IMPEDANCE BOARD

UNLESS OTHERWISE SPECIFIED	SIGNATURES		DATE
DIMENSIONS ARE IN INCHES	DRAWN	PLTO	02/02/17
TOLERANCES ON; ANGLES +/- 2°	CHECKED	NMIT	02/02/17
2 PL DECIMALS +/- .010	ENGRG	NMIT	02/02/17
3 PL DECIMALS +/- .005	ISSUED		
THIRD ANGLE PROJECTIONS			

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SAN JOSE, CA 95134
(408) 943-2600

FABRICATION DRAWING
CY8CKIT-146 PSoC 4200DS PROTOTYPING KIT

SIZE	FSCM NO	DWG NO	REV
C		610-60341-01	05

SCALE: 1/1 SHEET: 1 OF 2